

Material Content Data Sheet

RoHS

Sales Product Name	SGD02N60	**Issued**	18. August 2021
MA#	MA000269720		
Package	PG-TO252-3-11	**Weight***	363.83 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.871	0.24	0.24	2394	2394
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		178	
	non noble metal	iron	7439-89-6	0.215	0.06		592	
	non noble metal	copper	7440-50-8	215.017	59.08	59.16	590988	591758
wire	non noble metal	aluminium	7429-90-5	0.634	0.17	0.17	1741	1741
encapsulation	organic material	carbon black	1333-86-4	1.230	0.34		3381	
	inorganic material	antimonytrioxide	1309-64-4	2.460	0.68		6762	
	plastics	brominated resin	-	2.460	0.68		6762	
	plastics	epoxy resin	-	24.603	6.76		67624	
	inorganic material	silicondioxide	60676-86-0	92.263	25.36	33.82	253591	338120
leadfinish	non noble metal	tin	7440-31-5	3.740	1.03	1.03	10280	10280
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	250	251
solder	non noble metal	tin	7440-31-5	0.019	0.01		54	
	noble metal	silver	7440-22-4	0.024	0.01		67	
	non noble metal	lead	7439-92-1	0.930	0.26	0.28	2555	2676
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			16	
	non noble metal	iron	7439-89-6	0.019	0.01		53	
	non noble metal	copper	7440-50-8	19.177	5.27	5.28	52711	52780
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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